

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: H. MATSUURA, et al.
Application No.: 10/519,713
Filed: DECEMBER 30, 2004
For: ADHESIVE FILM FOR SEMICONDUCTOR USE, METAL
SHEET LAMINATED WITH ADHESIVE FIL, WIRING CIRCUIT
LAMINATED WITH ADHESIVE FILM, AND SEMICONDUCTOR
Group AU: 2823
Examiner: Julio J. Maldonado
Confirm. No.: 7508

AMENDMENT

Mail Stop: AMEND – NO FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

February 29, 2008

Sir:

In response to the Office Action mailed November 29, 2007, please amend
the above-identified application as listed in the following, and as set forth on the
following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.